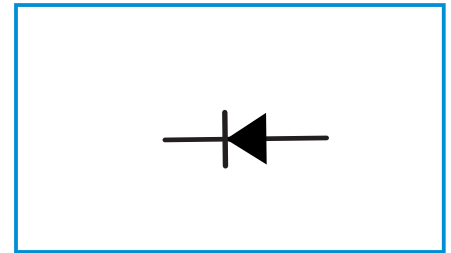


Surface Mount Schottky Barrier Rectifier

Features

- Metal silicon junction, majority carrier conduction
- For surface mounted applications
- Low power loss, high efficiency
- High forward surge current capability
- For use in low voltage, high frequency inverters, free wheeling, and polarity protection applications


Functional Diagram


Mechanical Data

- Case: SMBF
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 57mg / 0.002oz
- Polarity: Color band denotes cathode end
- Marking: SL54BF

Maximum Ratings and Electrical characteristics

Ratings at 25 °C ambient temperature unless otherwise specified.

Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20 %.

Parameter	Symbols	LT5E40	Units
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	40	V
Maximum RMS voltage	V_{RMS}	28	V
Maximum DC Blocking Voltage	V_{DC}	40	V
Maximum Average Forward Rectified Current	$I_{F(AV)}$	5.0	A
Peak Forward Surge Current, 8.3ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	I_{FSM}	130	A
Max Instantaneous Forward Voltage at 5 A	V_F	0.45	V
Maximum DC Reverse Current $T_j = 25^{\circ}C$ at Rated DC Reverse Voltage $T_j = 100^{\circ}C$	I_R	0.3 40	mA
Typical Junction Capacitance ¹⁾	C_j	280	pF
Typical Thermal Resistance ²⁾	$R_{\theta JA}$	45	$^{\circ}C/W$
Operating Junction Temperature Range	T_j	-55 ~ +150	$^{\circ}C$
Storage Temperature Range	T_{stg}	-55 ~ +150	$^{\circ}C$

(1) Measured at 1 MHz and applied reverse voltage of 4 V D.C

(2) P.C.B. mounted with 2.0" X 2.0" (5 X 5 cm) copper pad areas.

Ratings and characteristics Curves

Fig.1 Forward Current Derating Curve

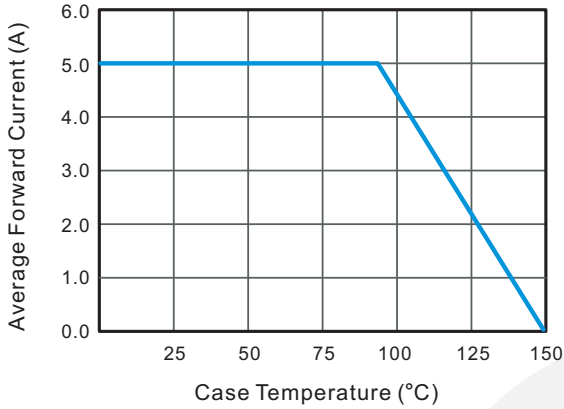


Fig.2 Typical Reverse Characteristics

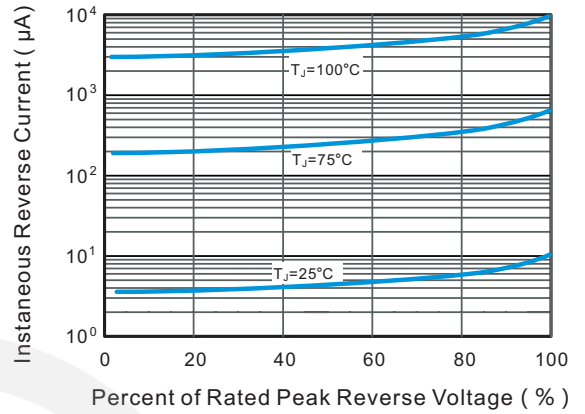


Fig.3 Typical Forward Characteristic

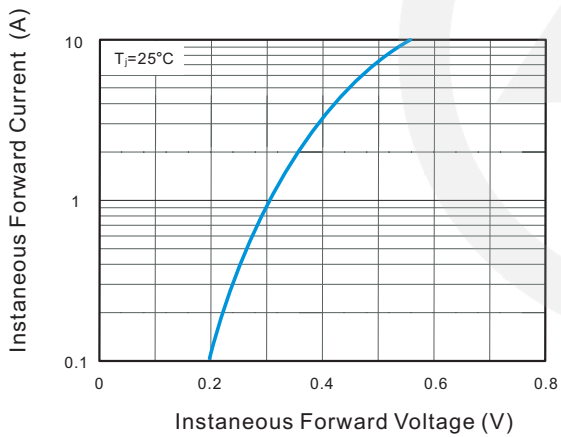


Fig.4 Typical Junction Capacitance

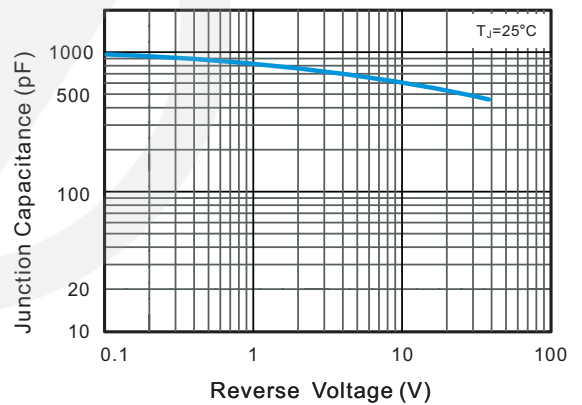


Fig.5 Maximum Non-Repetitive Peak Forward Surge Current

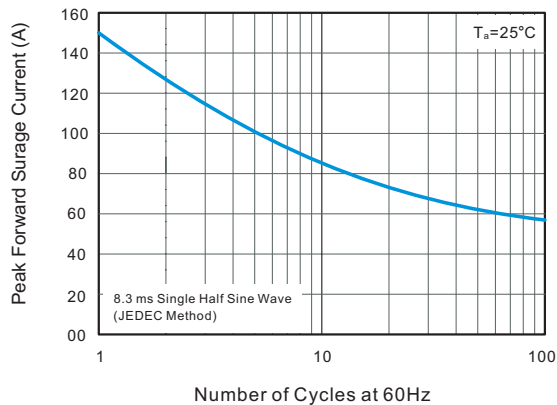
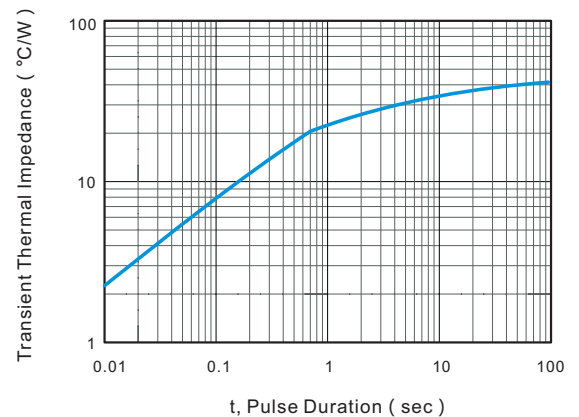
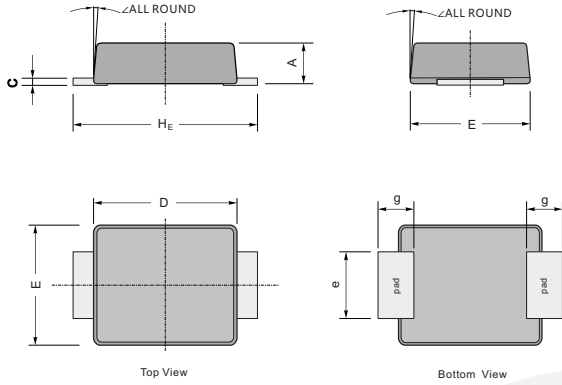


Fig.6- Typical Transient Thermal Impedance

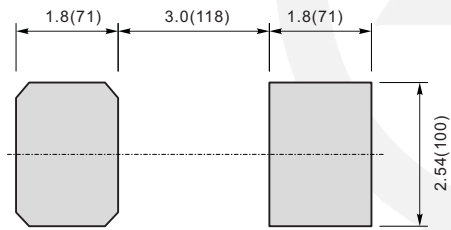


SMBF Package Outline

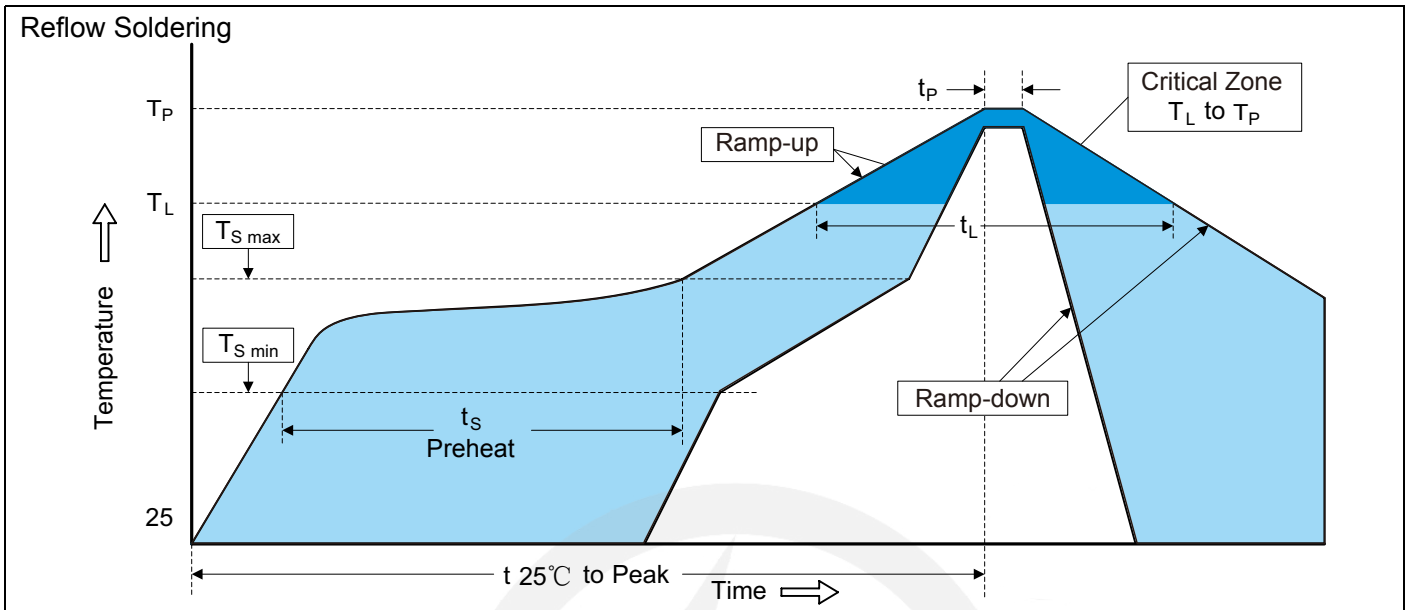


UNIT		A	C	D	E	H_E	e	g	\angle
mm	max	1.3	0.26	4.4	3.7	5.5	2.2	1.0	9°
	min	1.1	0.18	4.2	3.5	5.1	1.9		

SMBF Suggested Pad Layout



Unit: mm(mil)

Recommended Soldering Conditions

Recommended Conditions

Profile Feature	Pb-Free Assembly
Average ramp-up rate (T_L to T_P)	3°C/second max.
Preheat -Temperature Min ($T_{S\ min}$) -Temperature Max ($T_{S\ max}$) -Time (min to max) (t_s)	150°C 200°C 60-180 seconds
$T_{S\ max}$ to T_L -Ramp-up Rate	3°C/second max.
Time maintained above: -Temperature (T_L) -Time (t_L)	217°C 60-150 seconds
Peak Temperature (T_P)	260°C
Time within 5°C of actual Peak Temperature (t_P)	20-40 seconds
Ramp-down Rate	6°C/second max.
Time 25°C to Peak Temperature	8 minutes max.

Packaging

13" Reel


 D5 $\Phi 330.0 \pm 2.0$

 D6 $\Phi 13.5 \pm 0.5$

 H 2.5 ± 1.0

 W2 16.0 ± 2.0

Quantity: 5000PCS